TM-PCAB PHASE CHANGE MATERIAL

TM-PCAB is an excellent thermally conductive foil. It consists of a thin aluminium foil coated both sides with a thermally conductive phase change material. This coating changes its state at about 55°C and becomes soft expanding its volume and ensuring the best contact between the surfaces. So the material can fill the gap between the devices and heat sink completely, reducing the thermal resistance at minimum.

Properties

- Low heat resistance and low stress
- Low volatility – less than 1%
- Flowing but not silicone oil
- Self-adhesive, easy to use
- No radiator preheating

Application Examples

- High frequency microprocessors
- Chipset
- Bridge rectifiers
- Cache memory chips
- Graphic chips & Amplifiers chips

Physical Properties:

Test item	Unit	Test values
Colour		Black
Carrier		Aluminium Foil
Thermal Impedance	°C-in^2/W	0.03
Thermal Conductivity	W/m-K	2.5
Phase Change Temperature	°C	50 to 60
Density	g/cm^2	2.2
Total Thickness	mm	0.09
Storage Temperature	°C	<40
Temperature Range	°C	-45~125
Storage Time	Month	24

FUTURA srl - Via Tagliamento 16/18 – 20098 - Sesto Ulteriano - San Giuliano Milanese (MI)

- Tel: +39-029881193 Fax: +39-0298282216
  www.futura-italia.it info@futura-italia.it